

Product/Process Change Notification

N° 2021-060-A

Dear customer,

please find attached our Infineon Technologies AG PCN:

Change of parts of wafer production from Xintec Inc., Taoyuan City, Taiwan to Vanguard International Semiconductor Corporation, Hsinchu, Taiwan and corresponding equipment for products AUIPSx and AUIRx

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2022-01-26.
- Infineon aligns with the widely-recognized JEDEC STANDARD “JESD46”, which stipulates: “Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”
Notwithstanding the aforesaid individual agreements shall prevail.

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.



On 16 April 2020, Infineon acquired Cypress.

We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance.

For further details, please visit our website:

<https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/>

Infineon Technologies AG

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Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Constanze Hufenbecher, Dr. Sven Schneider

Registered Office: Neubiberg

Commercial Register: München HRB 126492

Product/Process Change Notification

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Products affected

Please refer to attached affected product list 1_cip21060_A



Detailed change information

Subject:

Change of parts of wafer production from Xintec Inc., Taoyuan City, Taiwan to Vanguard International Semiconductor Corporation, Hsinchu, Taiwan and corresponding equipment for products AUIPSx and AUIRx

Reason/Motivation:

Discontinuation of backside grinding and backside metallization process at Xintec

Description

	<u>Old</u>	<u>New</u>
PROCESS - WAFER PRODUCTION: Move all or parts of production to a different wafer fab site.	Xintec Inc., Taoyuan City, Taiwan	Vanguard International Semiconductor Corporation, Hsinchu, Taiwan
EQUIPMENT: Production from a new equipment/tool which uses a different basic technology or which due to its unique form or function can be expected to influence the integrity of the final product	Xintec toolpark	Vanguard toolpark

Product identification

Traceability assured via date code.
No change in SP ordering number

Anticipated impact of change

Based on the qualification performed, Infineon does not expect any negative impact on quality, function and reliability. No change in form, fit and function expected.

DeQuMa-ID(s): SEM-PW-13 / SEM-EQ-01

Attachments

1_cip21060_A affected product list

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Time schedule

Final qualification report	available
First samples available	on request
Intended start of delivery [1]	2022-06-20
Last order date (LOD) [2]	2022-06-20
Last delivery date (LDD) [3]	2022-12-31

[1] provided date or earlier after customer approval

[2] Last time buy volume to be placed latest until LOD

[3] Delivery of new product can be earlier (see Intended start of delivery) and depends on approval

If you have any questions, please do not hesitate to contact your local sales office.